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SEMICONDUCTOR

November 2013

## **FQP12P10 P-Channel QFET® MOSFET**

-100 V, -11.5 A, 290 mΩ

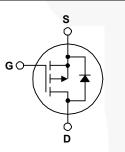
## Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize onstate resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.

### Features

- FQP12P10 P-Channel QFET<sup>®</sup> MOSFET • -11.5 A, -100 V,  $R_{DS(on)}$  = 290 m $\Omega$  (Max.) @ V<sub>GS</sub> = -10 V, I<sub>D</sub> = -5.75 A
- Low Gate Charge (Typ. 21 nC)
- Low Crss (Typ. 65 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





#### Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted.

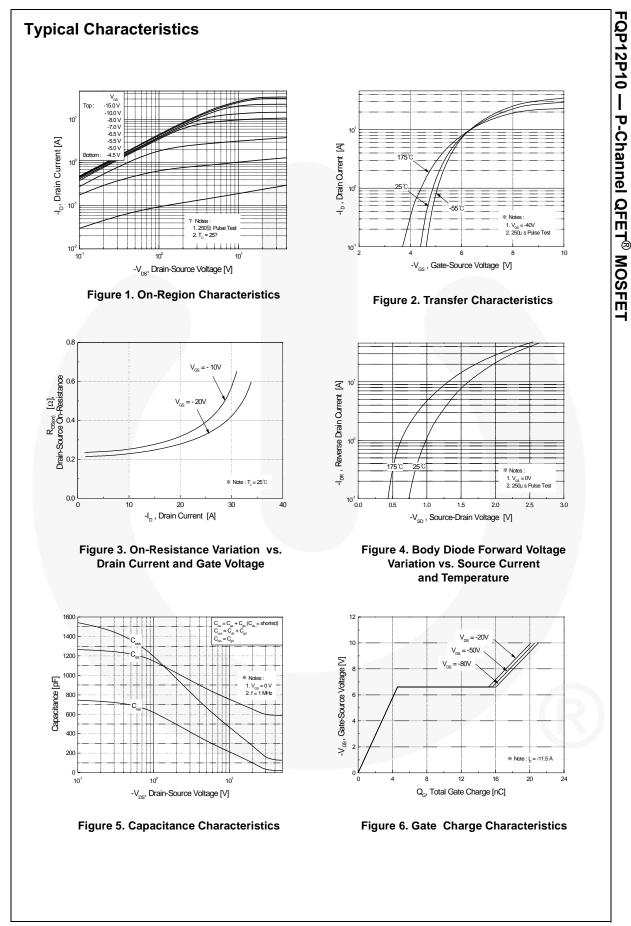
| Symbol                              | Parameter   | FQP12P10 | Unit        |      |
|-------------------------------------|---|----------|-------------|------|
| V <sub>DSS</sub>                    | Drain-Source Voltage  |          | -100        | V    |
| I <sub>D</sub>                      | Drain Current - Continuous (T <sub>C</sub> = 25°C)                  |          | -11.5       | A    |
| - Continuous (T <sub>C</sub> = 100° |   | )°C)     | -8.1        | A    |
| I <sub>DM</sub>                     | Drain Current - Pulsed  | (Note 1) | -46         | A    |
| V <sub>GSS</sub>                    | Gate-Source Voltage   |          | ± 30        | V    |
| E <sub>AS</sub>                     | Single Pulsed Avalanche Energy                                      | (Note 2) | 370         | mJ   |
| I <sub>AR</sub>                     | Avalanche Current   | (Note 1) | -11.5       | A    |
| E <sub>AR</sub>                     | Repetitive Avalanche Energy   | (Note 1) | 7.5         | mJ   |
| dv/dt                               | Peak Diode Recovery dv/dt   | (Note 3) | -6.0        | V/ns |
| P <sub>D</sub>                      | Power Dissipation (T <sub>C</sub> = 25°C)<br>- Derate above 25°C    |          | 75          | W    |
|                                     |   |          | 0.5         | W/°C |
| T <sub>J</sub> , T <sub>STG</sub>   | Operating and Storage Temperature Range                             |          | -55 to +175 | °C   |
| TL                                  | Maximum lead temperature for soldering 1/8" from case for 5 seconds | 300      | °C          |      |

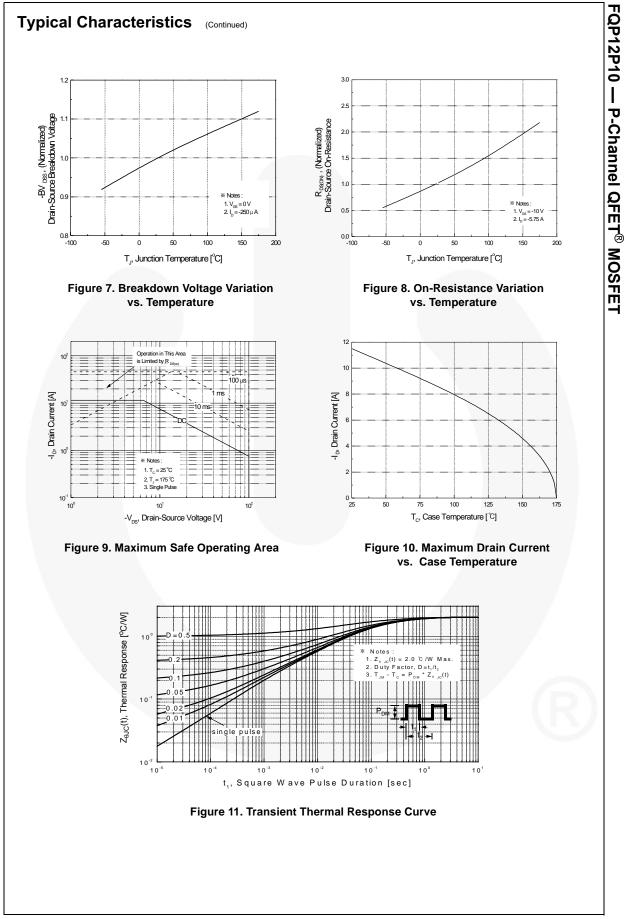
### **Thermal Characteristics**

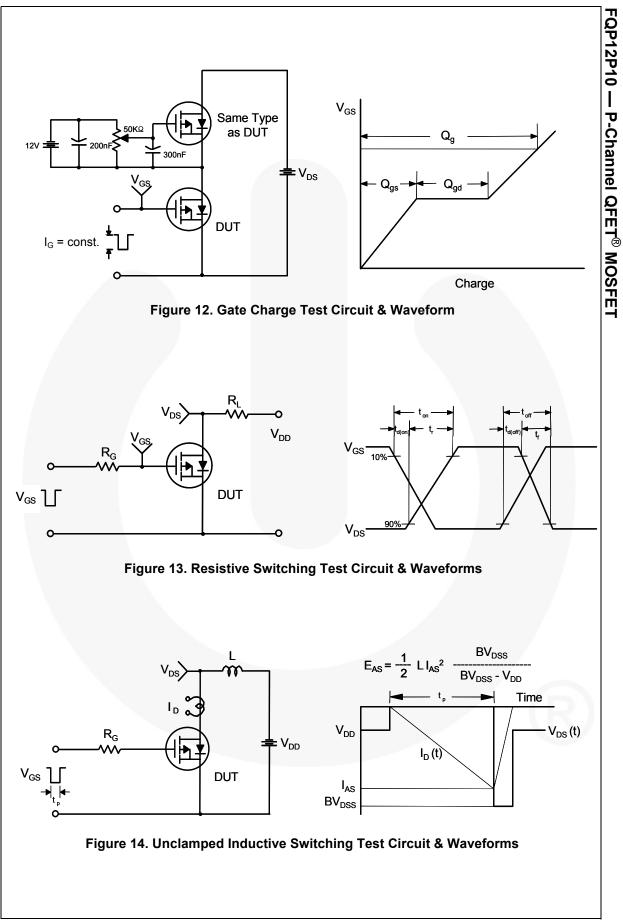
| Symbol                | Parameter                                     | FQP12P10 | Unit |
|-----------------------|---|----------|------|
| $R_{	extsf{	heta}JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 2.0      | °C/W |
| $R_{\theta CS}$       | Thermal Resistance, Case-to-Sink, Typ.        | 0.5      | °C/W |
| $R_{\theta JA}$       | Thermal Resistance, Junction-to-Ambient, Max. | 62.5     | °C/W |

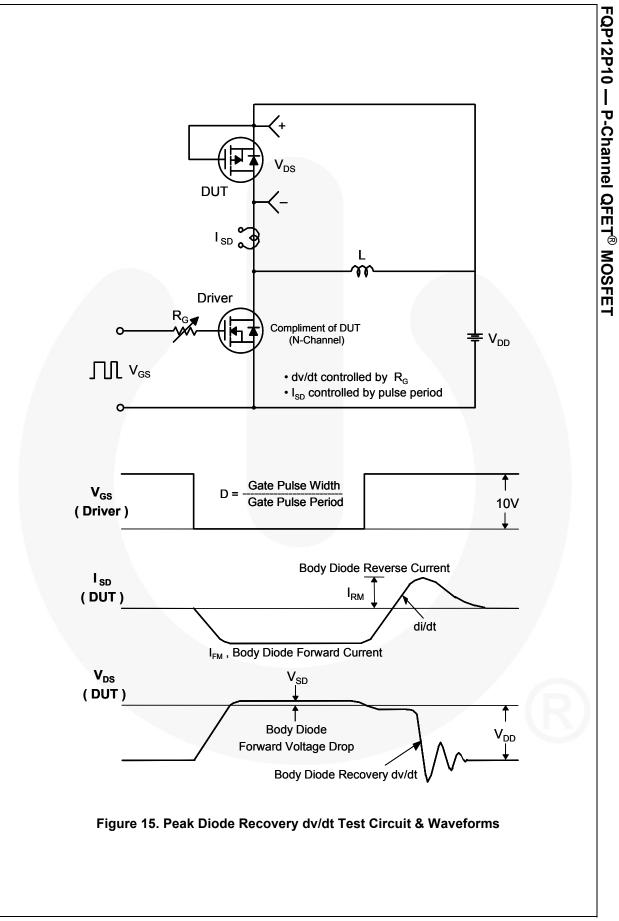
| rio FQP12P10<br>cal Characteristic<br>Parameter<br>racteristics<br>Drain-Source Breakdown  | <b>T</b> O-:<br><b>S</b> $T_c = 25^{\circ}C$ unl   |  | Packing Method<br>Tube  | N/A  | <b>\</b>  | N/A   |  |   |  |
|--|--|--|---|--|---|---|--|---|--|
| Parameter<br>racteristics<br>Drain-Source Breakdown  | <b>S</b> T <sub>c</sub> = 25°C unl   | ess otherwis   |   |  |   | 1 1/1 1   |  | Quantity<br>50 units  |  |
| <b>racteristics</b><br>Drain-Source Breakdown  |  |  | se noted.   |  |   |   |  |   |  |
| Drain-Source Breakdown   |  |  | Test Conditions   |  | Min   | Тур   | Max  | Unit  |  |
| Drain-Source Breakdown   |  |  |   |  |   |   |  |   |  |
|  | /oltogo  | $\lambda = 0$  | $1 = 250 \mu$   |  | -100  |   |  | V   |  |
| Dana ali davi va Malta da Tavada a   |  |  | $V_{GS} = 0 V, I_D = -250 \mu A$  |  | -100  |   |  | v   |  |
| Breakdown Voltage Temperature<br>Coefficient   |  | $I_D = -250 \ \mu\text{A}$ , Referenced to 25°C  |   |  | -0.1  |   | V/°C   |   |  |
| Zero Gate Voltage Drain Current  |  | -  |   |  |   |   | -1   | μA  |  |
| g  |  |  |   |  |   |   | -10  | μA  |  |
| Gate-Body Leakage Curre  | nt, Forward  |  |   |  |   | -100  | nA   |   |  |
| Gate-Body Leakage Curre  | nt, Reverse  | $V_{GS} = 3$   | 80 V, V <sub>DS</sub> = 0 V   |  |   |   | 100  | nA  |  |
|  |  |  |   |  |   |   |  |   |  |
|  | _  | N .  |   |  | 0.5   |   |  |   |  |
| 0  | _  | V <sub>DS</sub> = \  | $G_{\rm GS}, I_{\rm D} = -250 \mu{\rm A}$   |  | -2.0  |   | -4.0   | V   |  |
| On-Resistance  |  |  | 2   |  |   | 0.24  | 0.29   | Ω   |  |
| Forward Transconductance   | e  | $V_{DS} = -$   | 40 V, I <sub>D</sub> = -5.75 A  |  |   | 6.7   |  | S   |  |
| c Characteristics  |  |  |   |  |   |   |  |   |  |
| Input Capacitance  |  | $V_{DS} = -25 V, V_{GS} = 0 V,$<br>f = 1.0 MHz   |   |  |   | 620   | 800  | pF  |  |
| Output Capacitance   |  |  |   |  | 220   | 290   | pF   |   |  |
| Reverse Transfer Capacita  | ance   |  |   |  | 65  | 85  | pF   |   |  |
|  | _  |  |   |  |   |   |  |   |  |
| -  | _  |  |   |  |   | 1   |  |   |  |
|  | _  | V <sub>DD</sub> = -  | 50 V, I <sub>D</sub> = -11.5 A,   |  |   |   |  | ns  |  |
|  |  | R <sub>G</sub> = 25  | 5Ω  |  |   |   |  | ns  |  |
|  |  |  |   | (Note 4)   |   |   |  | ns  |  |
|  |  |  |   | (14010 4)  |   |   |  | ns  |  |
| Total Gate Charge  |  | $V_{DS} = -80 \text{ V}, I_D = -11.5 \text{ A},$<br>$V_{GS} = -10 \text{ V}$   |   |  |   | 21  | 27   | nC  |  |
| i cui cui churgo   |  |  |   |  |   | 4.6   |  | nC  |  |
| Gate-Source Charge   |  |  | (Note 4)  |  |   | 44 5  |  | nC  |  |
|  |  |  |   | (  |   | 11.5  |  | no  |  |
| Gate-Source Charge<br>Gate-Drain Charge  |  | V <sub>GS</sub> = -  |   | (  |   | 11.5  |  |   |  |
| Gate-Source Charge<br>Gate-Drain Charge<br>ource Diode Charact   |  | V <sub>GS</sub> = -  |   | (  |   | 11.5  |  |   |  |
| Gate-Source Charge<br>Gate-Drain Charge<br>ource Diode Charact<br>Maximum Continuous Drai  | n-Source Dic   | V <sub>GS</sub> = -  | ard Current   | (111.7)  |   |   | -11.5  | A   |  |
| Gate-Source Charge<br>Gate-Drain Charge<br>Ource Diode Charact<br>Maximum Continuous Drain<br>Maximum Pulsed Drain-Sc                            | n-Source Dic<br>ource Diode F  | V <sub>GS</sub> = -  | ard Current   |  |   |   | -11.5<br>-46   | A<br>A  |  |
| Gate-Source Charge<br>Gate-Drain Charge<br>Ource Diode Charact<br>Maximum Continuous Drai<br>Maximum Pulsed Drain-So<br>Drain-Source Diode Forwa | n-Source Dic<br>ource Diode F  | $V_{GS} = -$<br><b>nd Max</b><br>de Forward C<br>$V_{GS} = 0$  | ard Current<br>Current<br>O V, I <sub>S</sub> = -11.5 A   |  |   |   |  | A   |  |
| Gate-Source Charge<br>Gate-Drain Charge<br>Ource Diode Charact<br>Maximum Continuous Drain<br>Maximum Pulsed Drain-Sc                            | n-Source Dic<br>ource Diode F  | $V_{GS} = -$<br>and Max<br>and Forward C<br>$V_{GS} = (0)$<br>$V_{GS} = (0)$   | ard Current   |  |   |   | -46  | A<br>A  |  |
|  | Gate-Body Leakage Curre<br>Gate-Body Leakage Curre<br>racteristics<br>Gate Threshold Voltage<br>Static Drain-Source<br>On-Resistance<br>Forward Transconductance<br><b>C Characteristics</b><br>Input Capacitance<br>Output Capacitance<br>Reverse Transfer Capacita<br>ng Characteristics<br>Turn-On Delay Time<br>Turn-On Rise Time<br>Turn-Off Delay Time<br>Turn-Off Fall Time | Gate Threshold Voltage Static Drain-Source On-Resistance Forward Transconductance C Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ng Characteristics Turn-On Delay Time Turn-Off Delay Time Turn-Off Fall Time | Zero Gate Voltage Drain Current $V_{DS} = -$ Gate-Body Leakage Current, Forward $V_{GS} = -$ Gate-Body Leakage Current, Reverse $V_{GS} = -$ Gate-Body Leakage Current, Reverse $V_{GS} = -$ racteristics $V_{DS} = -$ Gate Threshold Voltage $V_{DS} = -$ Static Drain-Source $V_{DS} = -$ On-Resistance $V_{DS} = -$ Forward Transconductance $V_{DS} = -$ c CharacteristicsInput CapacitanceInput Capacitance $V_{DS} = -$ Output Capacitance $f = 1.0 \text{ If}$ Reverse Transfer Capacitance $V_{DS} = -$ f = 1.0 ITurn-On Delay TimeTurn-On Rise Time $V_{DD} = -$ Turn-Off Delay Time $V_{DD} = -$ Turn-Off Fall TimeTurn-Off Fall Time | VDS= -80 V, IC= 150°CGate-Body Leakage Current, Forward $V_{GS} = -30 V, V_{DS} = 0 V$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 V, V_{DS} = 0 V$ racteristics $V_{DS} = V_{GS}, I_D = -250 \mu A$ Gate Threshold Voltage $V_{DS} = -10 V, I_D = -5.75 A$ Static Drain-Source<br>On-Resistance $V_{DS} = -40 V, I_D = -5.75 A$ Forward Transconductance $V_{DS} = -40 V, I_D = -5.75 A$ Input Capacitance<br>Output Capacitance $V_{DS} = -25 V, V_{GS} = 0 V, f = 1.0 MHz$ Reverse Transfer Capacitance $V_{DS} = -25 V, V_{GS} = 0 V, f = 1.0 MHz$ Turn-On Delay Time<br>Turn-On Rise Time<br>Turn-Off Delay Time $V_{DD} = -50 V, I_D = -11.5 A, R_G = 25 \Omega$ | Zero Gate Voltage Drain Current $V_{DS} = -80 \text{ V}, \text{ T}_{C} = 150^{\circ}\text{C}$ Gate-Body Leakage Current, Forward $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ racteristics $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$ Static Drain-Source $V_{GS} = -10 \text{ V}, I_D = -5.75 \text{ A}$ On-Resistance $V_{DS} = -40 \text{ V}, I_D = -5.75 \text{ A}$ Forward Transconductance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ fuput Capacitance $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHzf = 1.0 MHzrurn-On Delay Time $V_{DD} = -50 \text{ V}, I_D = -11.5 \text{ A},$ Turn-Off Delay Time $V_{DD} = -50 \text{ V}, I_D = -11.5 \text{ A},$ rurn-Off Fall Time(Note 4) | Zero Gate Voltage Drain Current $V_{DS} = -80 \text{ V},  \text{T}_{C} = 150^{\circ}\text{C}$ Gate-Body Leakage Current, Forward $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ racteristics $V_{DS} = V_{GS}, \text{ I}_{D} = -250 \mu\text{A}$ Gate Threshold Voltage $V_{DS} = V_{GS}, \text{ I}_{D} = -250 \mu\text{A}$ Static Drain-Source $V_{GS} = -10 \text{ V}, \text{ I}_{D} = -5.75 \text{ A}$ On-Resistance $V_{DS} = -40 \text{ V}, \text{ I}_{D} = -5.75 \text{ A}$ Forward Transconductance $V_{DS} = -25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ C Characteristics $V_{DS} = -25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ Input Capacitance $V_{DS} = -25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ Output Capacitance $V_{DS} = -25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ reverse Transfer CapacitanceTurn-On Delay Time $V_{DD} = -50 \text{ V}, \text{ I}_{D} = -11.5 \text{ A},$ Turn-Off Delay Time $V_{DD} = -50 \text{ V}, \text{ I}_{D} = -11.5 \text{ A},$ Turn-Off Fall Time $(Note 4)$ Turn-Off Fall Time $(Note 4)$ | Zero Gate Voltage Drain Current $V_{DS} = -80 \text{ V},  \text{T}_{C} = 150^{\circ}\text{C}$ Gate-Body Leakage Current, Forward $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ racteristics $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ racteristics $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$ Gate Threshold Voltage $V_{DS} = V_{GS},      = -250  \mu \text{ A}$ -2.0Static Drain-Source<br>On-Resistance $V_{DS} = -10 \text{ V},     = -5.75 \text{ A}$ 0.24Forward Transconductance $V_{DS} = -40 \text{ V},        $ | $\begin{tabular}{ c c c c c c } \hline $V_{DS}$ = -80 V, $T_{C}$ = 150°C & & & -10 \\ \hline $Qate-Body Leakage Current, Forward $V_{GS}$ = -30 V, $V_{DS}$ = 0 V & & & -100 \\ \hline $Gate-Body Leakage Current, Reverse $V_{GS}$ = 30 V, $V_{DS}$ = 0 V & & & 100 \\ \hline $Gate-Body Leakage Current, Reverse $V_{GS}$ = 30 V, $V_{DS}$ = 0 V & & & 100 \\ \hline $Gate-Body Leakage Current, Reverse $V_{GS}$ = 30 V, $V_{DS}$ = 0 V & & & 100 \\ \hline $Gate-Body Leakage Current, Reverse $V_{GS}$ = 0 V, $V_{DS}$ = -250 $\mu$A & -2.0 & & -4.0 \\ \hline $Static Drain-Source $V_{DS}$ = -10 V, $I_{D}$ = -5.75 $A & & 0.24 $0.29 \\ \hline $On-Resistance $V_{DS}$ = -40 V, $I_{D}$ = -5.75 $A & & 6.7 $ \\ \hline $C Characteristics $V_{DS}$ = -40 V, $I_{D}$ = -5.75 $A & & 6.7 $ \\ \hline $C Characteristics $V_{DS}$ = -25 V, $V_{GS}$ = 0 V, $f = 1.0 $MHz$ & & 65 $85 \\ \hline $Mg Characteristics $V_{DS}$ = -25 V, $V_{GS}$ = 0 V, $f = 1.0 $MHz$ & & 65 $85 \\ \hline $Mg Characteristics $V_{DD}$ = -50 V, $I_{D}$ = -11.5 $A, $ $15 $40 $ $160 $330 $ $35 $80 $ $ |  |

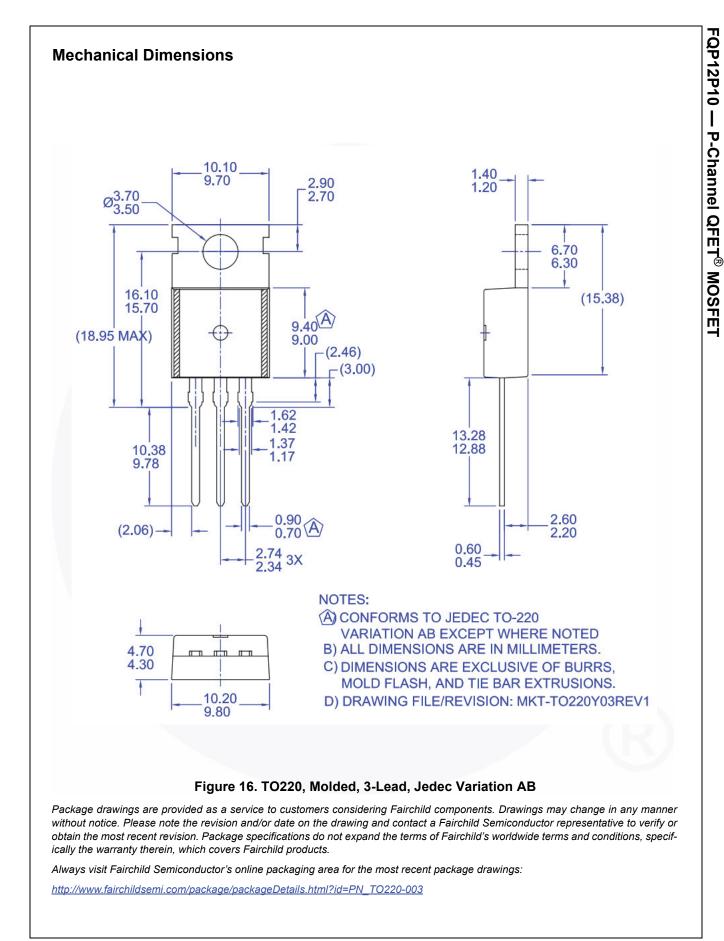
FQP12P10 — P-Channel QFET<sup>®</sup> MOSFET













| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
|--------------------------|-----------------------|---|
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